
PRODUCT CHANGE NOTICE

**Alternate Manufacturing Site for
Assembly of Intersil
ISL62882CHRTZ* and
ISL62883CHRTZ* TQFN Packaged
Products**

**Refer to:
PCN11048A**

Date: June 27, 2011

June 27, 2011

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Site for Assembly of Intersil ISL62882CHRTZ* and ISL62883CHRTZ* TQFN Packaged Products** – *Advanced Semiconductor Engineering - Chung-Li, Taiwan (ASECL)*

PCN11048A is being issued to inform customers that Intersil has updated the list of affected products contained in notice PCN11048 that was issued on May 9, 2011. The ISL62882CIRTZ, ISL62882CIRTZ-T, ISL62883CIRTZ, and ISL62883CIRTZ-T products have been removed from the notice. As such, the changes outlined in PCN11048 will not be implemented for those products. The content of the original notice, PCN11048, with the updated product list is included below for reference.

This notice is to inform you that Intersil will begin using the Advanced Semiconductor Engineering (ASECL) facility as an alternate site for assembly of the ISL62882CHRTZ* and ISL62883CHRTZ* TQFN (Thin Quad Flat No-Lead) packaged products. Products manufactured at the ASECL facility will be assembled using copper bond wire as an alternate to the gold wire currently used today. The advantages of copper bond wire include improved electrical conductivity of the wire, slower intermetallic growth, reduced wire sweep, and equivalent reliability performance. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The product and site-specific qualification activities are complete.

Products affected:

ISL62882CHRTZ ISL62882CHRTZ-T ISL62883CHRTZ ISL62883CHRTZ-T

The Advanced Semiconductor Engineering (ASECL) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and qualified as a supplier to Intersil for assembly of TQFN packaged products with both copper and gold bond wire material. There will be no change in the package outline drawing (POD). Products assembled with copper bond wire are classified as moisture sensitivity level three (MSL 3 at 260°C per J-STD-020). The qualified material set combinations for assembly are as follows:

Material	Current	ASECL
Mold Compound	Sumitomo EME-G770HCD	Sumitomo EME-G770HJ
Die Attach	Sumitomo CRM-1076NS	Hysol QMI 519
Bond Wire	1.0 mil Gold (Au)	1.0 mil Copper (CU) w/ Palladium (Pd) Coat

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at ASECL may also be identified by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at ASECL with copper bond wire is "W".

Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive the listed products assembled at either the current or the newly qualified sites beginning *ninety* days from the date of the original notice, May 9, 2011, or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,



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Intersil Corporation

PCN11048A

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